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# TABLE OF CONTENTS

<b>Characterization and Modeling of a Typical Curing Material for Photoresist Films</b> .....	1
<i>Chongnan Peng; Matthias Morak; Andreas Thalhamer; Mario Gschwandl; Peter Fuchs; Qi Tao; Thomas Krivec; Thomas Antretter; Miguel Angel Celigueta</i>	
<b>Digital Twin for Controlled Generation of Water-In-Oil Microdroplets with Required Size</b> .....	8
<i>Nafisat Gyimah; Ott Scheler; Toomas Rang; Tamas Pardy</i>	
<b>Increased Breakdown Voltage and Robustness of Embedded Power Module</b> .....	15
<i>A. Tablati; N. Alayli; F. Arabi; K. El Boubakari; T. Youssef; L. Theolier; E. Woirgard</i>	
<b>Performance Assessment of Different Machine Learning Algorithm for Life-Time Prediction of Solder Joints Based on Synthetic Data</b> .....	23
<i>S. Muench; D. Bhat; L. Heindel; P. Hantschke; M. Roellig; M. Kaestner</i>	
<b>Interaction of Advanced Copper Metallization with the Assembly and Interconnection Technology</b> .....	33
<i>Daniel Losbichler; Markus Klingler; Steffen Orso; Bernhard Wunderle</i>	
<b>Thermal Aging on Molding Compounds: Material Characterization and Modeling</b> .....	43
<i>Luca Grandi; Marco Rovitto</i>	
<b>Shift of Die Passivation by Ratcheting of Underlying Aluminum Bond Pads</b> .....	52
<i>M. Van Soestbergen; Y. Chen; T. Hauck</i>	
<b>Analysis of Stress in Spherically Bent Thinned Image Sensors</b> .....	59
<i>Amit Pandey; Sri Krishna Bhogaraju; Kerstin Lux; Gordon Elger</i>	
<b>Novel Method for Modelling the Local Electro-Thermal Behaviour of Discrete Power Diode Using Verilog-A in a Standard CAD Environment</b> .....	64
<i>Achraf Kaïd; Jean-Baptiste Kammerer; Fabrice Roqueta; Luc Hébrard</i>	
<b>Determination of Rate- And Temperature Dependent Inelastic Material Data for Sintered Silver Die Attach and Simulative Implementation</b> .....	71
<i>Freerik Forndran; Jens Heilmann; Martin Metzler; Markus Leicht; Bernhard Wunderle</i>	
<b>Novel Methodology for 3D FEM Modeling of Wire Bonding Process by Ball Deformation Reproduction</b> .....	77
<i>L. Guarino; C. Caglio; R. Villa; L. Zullino; L. Cecchetto</i>	
<b>High Speed Thermal Mapping on Six-Pack SiC-Based Module for Hybrid and Electric Vehicles</b> .....	83
<i>Giuliana Malta; Laura Anoldo; Bruna Mazza; Giuseppe G. Piccione; Alfio Russo; Michele Calabretta; Sebastiano Russo; Alessandro Sitta; Angelo Messina; Antonio Lionetto; Salvatore Patanè</i>	
<b>A Simulation-Based Assessment of Print Accuracy for Microelectronic Parts Manufactured with DLP 3D Printing Process</b> .....	88
<i>A. Thalhamer; P. Fuchs; L. Strohmeier; S. Hasil; A. Wolfberger</i>	
<b>Physicochemical-Microstructural Approach for Modeling the Crack Passage at Topside Metallic Parts in IGBT Semiconductor Power Electronics</b> .....	99
<i>M. Shqair; Z. Khatir; A. Ibrahim; M. Berkani; A. Halouani; T. Hamieh</i>	
<b>A Capacitive MEMS Energy Harvester for Shock-Induced Periodic Excitations</b> .....	105
<i>Bogdan Vysotskyi; Veronique Rochus</i>	
<b>Multi-Mode Weibull Probability Density Function for Clustered Die Strength Data</b> .....	110
<i>S. Ananiev; G. M. Reuther; K. Unterhofer; P. Altieri-Weimar</i>	
<b>Apparent Heat Capacity Model of the SiC MOSFET's Aluminium Top Surface for Short-Circuits Simulations</b> .....	112
<i>F. Loche-Moinet; L. Theolier; E. Woirgard</i>	
<b>Low Cycle Fatigue of Thin Metal Films on Vibrating Silicon MEMS Cantilevers: Finite Element Modelling Facilitating Experimental Design</b> .....	118
<i>Nadine Pflügler; Sebastian Breitenreiner; Reinhard Pufall; Bernhard Wunderle</i>	
<b>A PoF Based Methodology to Assess the Reliability of a Sensor Module Operating in Harsh Industrial Environments</b> .....	123
<i>Chimmay Nawghane; Bart Vandevelde; Riet Labie; Sam Michiels; Danny Hughes; Mengyao Liu</i>	
<b>Piezoelectric Flexible Haptic Interface Development</b> .....	129
<i>Romain Le Magueresse; Fabrice Casset; Frédéric Giraud; Brigitte Desloges; Nadine David; Anis Kaci; Adélaïde Berdagué; Mikael Colin</i>	
<b>GaN HEMTs Thermal Time Constants: Theory and Measurements</b> .....	134
<i>Anass Jakani; Raphael Sommet; K. Karrame; Jean-Christophe Nallatamby</i>	
<b>Efficient Modeling of Acoustic Channels – Towards Tailored Frequency Response of Airborne Ultrasonic MEMS Transducers</b> .....	139
<i>Gabriele Bosetti; Gabriele Schrag</i>	

<b>In-Situ Reliability Monitoring of Power Packages Using a Thermal Test Chip</b> .....	144
<i>H. A. Martin; R. Sattari; E. C. P. Smits; H. W. Van Zeijl; W. D. Van Driel; G. Q. Zhang</i>	
<b>High Power Module GaN with Integrated Current Sensor for Fast Short Circuit Protection</b> .....	154
<i>Thanh Long Le; Jean Sylvio Ngoua Teu; Toni Youssef</i>	
<b>Continuous AI-Aided Learning to Establish the Digital Twin Models for Predicting the Individual Reliability Characteristics</b> .....	161
<i>Cadmus Yuan</i>	
<b>Pressing Simulations Within the PCB Manufacturing Framework</b> .....	165
<i>Christian Schipper; Peter Fuchs; Matthias Morak; Qi Tao; Julia Zuendel</i>	
<b>Data Augmentation for Improved Stress Prognostics for Encapsulated Standard Packages by Neural Networks Using Data from In-Situ Condition Monitoring During Thermal Shock Tests</b> .....	170
<i>Peter Meszner; Alexandru Prisacaru; Przemyslaw Jakub Gromala; Bernhard Wunderle</i>	
<b>Hard Encapsulation of Automotive Power Modules by Epoxy Potting – Encapsulant Selection Assisted by Thermo-Mechanical Simulation</b> .....	181
<i>M. Sprenger; F. Forndran; B. Ottinger; T. Dammann; B. Erben; M. Sippel; J. Franke</i>	
<b>Characterization of Interfacial Parameters for Lifetime Modelling in Modern Optical Sensor Package Assemblies</b> .....	187
<i>R. Kniely; F. Huber; J. Heilmann; M. Schulz; B. Wunderle</i>	
<b>Damage Evolution in SAC Solder Alloys</b> .....	201
<i>Yaxiong Chen; Torsten Hauck; Abdullah Fahim; Mohammad Ashrafal Haq; Mohd Aminul Hoque; Jeffrey C. Suhling</i>	
<b>Virtual Testing and Digital Twin Approaches for Response of Grain-Scale Solder Interconnects to Multiaxial Loading</b> .....	210
<i>Torsten Hauck; Michiel Van Soestbergen; Qian Jiang; Abhishek Deshpande; Aniket Bharamgonda; Abhijit Dasgupta</i>	
<b>Inline Failure Analysis of Sintered Layers in Power Modules Using Infrared Thermography</b> .....	217
<i>S. Panahandeh; D. May; C. Grosse-Kockert; A. Stelzer; B. Rabay; D. Busse; B. Wunderle; M. Abo Ras</i>	
<b>An Advanced, Systematic Simulation Approach for Studying Warpage Drivers of an Assembled Printed Circuit Board in Early Development Stage</b> .....	224
<i>M. Frewein; S. Stojanovic; Q. Tao; T. Krivec; J. Zuendel; M. Goessler; P. F. Fuchs; M. Gschwandl</i>	
<b>Finite-Element Modeling of the Visco-Plastic Shear-Dominant Deformation Behavior of a Creep-Resistant Sn-Based Solder Alloy Under TMF Testing</b> .....	233
<i>Jonas Gleichauf; Youssef Maniar; Marta Kuczynska; René Metasch; Mike Roellig; Steffen Wiese</i>	
<b>Liquid Cooling Solutions for Automotive HPC: Thermal Path Characterisation</b> .....	241
<i>Tobias Grün; Daniel May; Hubert Straub; Gromala Przemyslaw Jakub; Bernhard Wunderle; Willem Verleysen</i>	
<b>Wafer Bifurcation as a Spontaneous Symmetry Breaking</b> .....	248
<i>Vincenzo Vinciguerra; Antonio Landi; Giuseppe Luigi Malgioglio</i>	
<b>Models of Bifurcation in a Semiconductor Wafer: A Comparison of the Analytical Solution Vs. the ANSYS Finite Element Analysis</b> .....	251
<i>Vincenzo Vinciguerra; Giuseppe Luigi Malgioglio; Antonio Landi</i>	
<b>Macro- And Microscopic DMA Measurements - Complementary Techniques to Determine Viscoelastic Material Properties of Packaging Polymers</b> .....	255
<i>A. Clausner; S. Schlipf; C. Sander; R. Schwerz; M. Roellig</i>	
<b>Packaged Thermoelectric Generator with High-Aspect-Ratio Thermocouple Legs for Electrically Active Implants</b> .....	261
<i>Yongchen Rao; Chu Xu; Tamara Bechtold; Dennis Hohlfeld</i>	
<b>Failure Strength Analysis and Young Modulus Assessment of 4H-SiC Through a Ball on Ring Test</b> .....	265
<i>Vincenzo Vinciguerra; Antonio Landi; Herbert Hintermaier; Paolo Badalà; Gerald Klug; Alessandro Sitta; Michele Calabretta; Anna Bassi; Marco Renna; Angelo Alberto Messina</i>	
<b>Thermal Heat Path Signature of a Standard D2PAK Power Package by Transient Thermal Characterization and Modelling</b> .....	271
<i>Maik Sternberg; Kaushal Arun Pareek; Daniel May; Mohamad Abo Ras; Bernhard Wunderle</i>	
<b>Reliability Analysis with Fragility Surfaces and a Workflow for Antifragility</b> .....	277
<i>Roland Niemeier</i>	
<b>Numerical Simulation of a Thermoelectric Generator Using the Open-Source Software FEniCSx</b> .....	281
<i>Gunasheela Sadashivaiah; Yongchen Rao; Dennis Hohlfeld</i>	
<b>Durability of Copper Traces in Ball Grid Array (BGA) Assemblies Under Sequential Harmonic Vibration and Temperature Cycling</b> .....	285
<i>Idowu Olatunji; Abhishek Deshpande; Manuel Bascolo; Abhijit Dasgupta; Ulrich Becker; Gabor Jokai</i>	
<b>In-Situ Method for Fatigue Life Assessment Subjected to Surface Strain</b> .....	290
<i>Markus Käß; Hendrik Schmidt; Roland Lichtinger</i>	

<b>Deep Learning-Based Multiscale Modelling of Polysilicon MEMS</b> .....	296
<i>José Pablo Quesada-Molina; Stefano Mariani</i>	
<b>Model Order Reduction of a Thermo-Mechanical Packaged Chip Model for Automotive MOSFET Applications</b> .....	303
<i>C. B. Umunnakwe; I. Zawra; C. Yuan; E. B. Rudnyi; D. Hohlfeld; M. Niessner; T. Bechtold</i>	
<b>Design, Fabrication and Characterization of High-G Acceleration Sensors for Automotive Industry and Test Structures for the Process Characterization</b> .....	308
<i>Alexey Shaporin; Sebastian Weidlich; Dirk Wunsch; Susann Hahn; Roman Forke; Karla Hiller; Harald Kuhn</i>	
<b>From Wafer Bifurcation to Warpage Die: A Correlation Method to Determine the Warpage of a Metal-Coated Silicon Substrate</b> .....	315
<i>Vincenzo Vinciguerra; Giuseppe Luigi Malgioglio; Antonio Landi; Salvatore Valastro; Brunella Cafra; Marco Renna</i>	
<b>Inline Tilt Measurements of Sintered Dies by Optical Line Scanning as Quality Assessment Tool for Smart Production</b> .....	321
<i>D. May; J. Heilmann; M. Schulz; E. Boschman; M. Abo Ras; B. Wunderle</i>	
<b>Finite Element Supported Data Augmentation for a Deep Learning Driven Intelligent Failure Analysis System Based on Infrared Thermography</b> .....	328
<i>Kaushal Arun Pareek; Daniel May; Peter Meszmer; Mohamad Abo Ras; Bernhard Wunderle</i>	
<b>Numerical Simulation of Transient Thermomechanical Ageing Effects</b> .....	336
<i>Marius Van Dijk; Saskia Huber; Hans Walter; Olaf Wittler; Martin Schneider-Ramelow</i>	
<b>Humidity and Corrosion Susceptibility of Molded Packages Under Mechanical Impact Novel Package Level Impact Test to Provoke Micro-Damage</b> .....	342
<i>Dominik Udiljak; Reinhard Pufall; Georg M. Reuther; Jamila Boudaden; Peter Ramm; Gabriele Schrag</i>	
<b>Application of Finite Element Simulations for the Determination of Defects in Electrical Interconnections in Power Modules</b> .....	350
<i>H. Huai; J. Wilde</i>	
<b>Investigation of the Impact of Thermal Aging of Molding Compounds on the Solder Joint Fatigue of a VQFN Package</b> .....	355
<i>Maofen Zhang; Yuen Sing Chan; Niessner Martin Richard; Schuetz Gerhard; Altieri-Weimar Paola; Bernhard Wunderle</i>	
<b>Interaction of Advanced Copper Metallization with the Assembly and Interconnection Technology</b> .....	364
<i>Daniel Losbichler; Markus Klingler; Steffen Orso; Bernhard Wunderle</i>	
<b>Modelling Thermal Fatigue in Power Electronics</b> .....	373
<i>Rainer Dudek; Ralf Döring; Anu Mathew; Alexander Otto; Sven Rzepka</i>	
<b>Evaluation of SAC Solder Joint Thermomechanical Fatigue in Different Types of Components</b> .....	384
<i>E. Ben Romdhane; P. Roumanille; A. Guédon-Gracia; S. Pin; P. Nguyen; H. Frémont</i>	
<b>Experimental Study of Transient Heat Transfer and Temperature Dynamics in the Electronics Enclosures</b> .....	390
<i>Z. Staliulionis; L. Paukštaitis; G. Miliauskas</i>	
<b>Dynamics of the Corrosion for SAC305 Solder Alloy in Salt Environment</b> .....	397
<i>K. E. Akoda; A. Guédon-Gracia; E. Lebraud; J.-Y. Delétage; B. Plano; H. Frémont</i>	
<b>Optimized TMF Measurement Setup for Reproducible Lifetime Measurements on Solder Joints Under Accelerated Thermal-Mechanical Conditions</b> .....	403
<i>R. Metasch; M. Roellig; R. Schwertz; J. Gleichauf; Y. Maniar; R. Ratchev; K. Meier</i>	
<b>Structural-Thermal-Optical-Performance (STOP) Analysis of a Lens Stack for Realization of a Digital Twin of an Automotive LiDAR</b> .....	409
<i>M. Tavakolibasti; P. Meszmer; M. Kettelgerdes; G. Bötger; G. Elger; H. Erdogan; A. Seshaditya; B. Wunderle</i>	
<b>Electrical Diagnostics of Passive Components Failure During Reliability Testing</b> .....	416
<i>E. Wiss; R. Metasch; D. Barth; V. Serea; M. Roellig; S. Wiese</i>	
<b>High-Cycle Fatigue Testing of Thin Metal Films on MEMS Cantilever</b> .....	424
<i>N. Jöhrmann; C. Stöckel; B. Wunderle</i>	
<b>PMUT Array Design for Mid-Air Haptic Feedback</b> .....	430
<i>Margo Billen; Pieter Gijsenbergh; Eloi M. Ferrer; Mohan S. Pandian; Xavier Rottenberg; Veronique Rochus</i>	
<b>Numerical Simulation of a Wire Bond Shear Test Using Nonlinear Adaptive Remeshing</b> .....	436
<i>Simon Kuttler; Olaf Wittler; Martin Schneider-Ramelow</i>	
<b>A Numerical and Experimental Investigation of Influential Factors for Solder Joint Reliability of Power LEDs for Automotive Applications</b> .....	439
<i>Mehrdad Shaygi; Muyuan Li; Kurt-Jürgen Lang; Harald Laux; Bernhard Wunderle</i>	
<b>Effects of Shell Thickness on the Thermal Stability of Cu-Ag Core-Shell Nanoparticles: A Molecular Dynamics Study</b> .....	448
<i>Shizhen Li; Xu Liu; Jing Jiang; Chunjian Tan; Chenshan Gao; Yang Liu; Huaiyu Ye; Guoqi Zhang</i>	

<b>Towards Predictive System-Level Modelling of Miniaturized Photoacoustic Gas Sensors</b> .....	453
<i>Simon Essing; Gabriele Schrag; David Tumpold; Christoph Glacer; Michael Mihotek; Andrey Kravchenko</i>	
<b>2D Model for Moisture Diffusion in Integrated Low-K Dielectrics</b> .....	458
<i>Léo Mischler; Vivien Cartailier; Genevieve Duchamp; H��l��ne Fremont; Gr��gory Imbert; J. B. Moulard; Olivier Kermarrec</i>	
<b>Investigation of FPGA and SRAM Cells Under Radiation Exposure</b> .....	464
<i>Kirsten Weide-Zaage; Guillermo Paya-Vaya; Katharina Schmidt; Dorian Hagenah</i>	
<b>A Physics-Based Interpolation Method for Rapid Dimensioning of pMUT Designs</b> .....	469
<i>Aleksander Bajt; Gabriele Bosetti; Prajith Kumar Poongodan; Gabriele Schrag; Frank Vanselow</i>	
<b>Epoxy Mold Compound Characterization for Modeling Packaging Reliability</b> .....	474
<i>Ariane Tomas; Benoit Lambert; H��l��ne Fr��mont; Nathalie Malbert; Nathalie Labat</i>	
<b>Vibration Sensors with a High Bandwidth and Low SNR, Enhanced with Post Processing Gap Reduction</b> .....	479
<i>Petra Streit; Roman Forke; Sven Voigt; Uwe Schwarz; Roman Ziegenhardt; Sebastian Weidlich; Detlef Billep; Markus Gaitzsch; Harald Kuhn</i>	
<b>Reduced Order Modelling of a Neuron-Electrode Interface</b> .....	486
<i>Ulrike Fitzer; Dennis Hohlfeld; Tamara Bechtold</i>	
<b>Ultrasonic Piezoelectric Mems Speakers for In-Ear Applications: Bubbles-Like and Pistons-Like Innovative Designs</b> .....	492
<i>G. Massimino; C. Gazzola; V. Zega; S. Adorno; A. Corigliano</i>	
<b>Exchanging Thermo-Mechanical Simulation Models Independent on FEM Software Platform</b> .....	496
<i>Bart Vandeveld; Chinmay Nawghane; Rainer Dudek; Ralf D��ring; Jens Schindele; Przemyslaw Gromala</i>	
<b>Deep Learning Modelling for Composite Properties of PCB Conductive Layers</b> .....	503
<i>Stoyan Stoyanov; Chris Bailey</i>	
<b>Performance Comparison for Stable Compact Modelling of Piezoelectric Microactuator</b> .....	510
<i>Arwed Sch��tz; Tamara Bechtold</i>	
<b>Heterogeneous Integration of Chipllets: Cost and Yield Tradeoff Analysis</b> .....	518
<i>Mudasir Ahmad; Javi Delacruz; Anu Ramamurthy</i>	
<b>Design Optimization for Passivation Crack Improvement in Power Devices</b> .....	527
<i>Haibo Fan; Zhou Zhou; Yuning Shi; Ivan Shiu; Jun Yang; Haibin Chen</i>	
<b>High-Voltage and High-Current IGBT Press-Pack Module for Power Grid</b> .....	531
<i>Chunjian Tan; Shaogang Wang; Xu Liu; Jing Jiang; Guoqi Zhang; Huaiyu Ye</i>	
<b>BGA Solder Strain Prediction Using an Artificial Neural Network Regressor</b> .....	535
<i>Pablo Ferrando-Villalba; Bart Vandeveld</i>	
<b>Author Index</b>	